

Product Summary

| Device | V _{(BR)DSS} | R _{DS(ON)} | I _D T _A = +25°C |
|--------|----------------------|---------------------------------|---------------------------------------|
| Q1 | 20V | 0.45Ω @ V _{GS} = 4.5V | 1066mA |
| Q2 | | 0.75Ω @ V _{GS} = -4.5V | -845mA |

Description

This new generation MOSFET has been designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

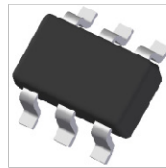
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Power Supply Converter Circuits

Features and Benefits

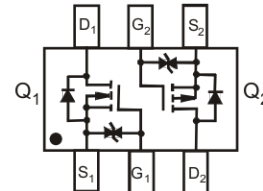
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- ESD Protected Up to 2.5kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- Qualified to AEC-Q101 standards for High Reliability**

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 **Ⓔ**
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)



Top View



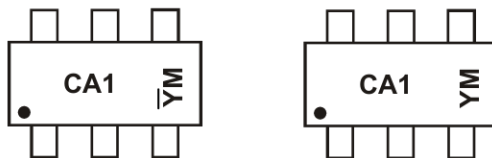
Top View
Internal Schematic

Ordering Information (Note 4)

| Part Number | Compliance | Case | Packaging |
|---------------|------------|--------|------------------|
| DMG1016UDW-7 | Standard | SOT363 | 3000/Tape & Reel |
| DMG1016UDWQ-7 | Automotive | SOT363 | 3000/Tape & Reel |

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 - See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



CA1 = Product Type Marking Code
 YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
 YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)
 Y or Ȳ = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

| Year | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 |
|------|------|------|------|------|------|------|------|------|------|
| Code | V | W | X | Y | Z | A | B | C | D |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|--|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 5) | P _D | 330 | mW |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{θJA} | 379 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Maximum Ratings N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|-----------------------------------|------------------|------------------------|-------|
| Drain-Source Voltage | V _{DSS} | 20 | V |
| Gate-Source Voltage | V _{GSS} | ±6 | V |
| Continuous Drain Current (Note 5) | I _D | T _A = +25°C | 1066 |
| | | T _A = +85°C | 690 |

Maximum Ratings P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|-----------------------------------|------------------|------------------------|-------|
| Drain-Source Voltage | V _{DSS} | -20 | V |
| Gate-Source Voltage | V _{GSS} | ±6 | V |
| Continuous Drain Current (Note 5) | I _D | T _A = +25°C | -845 |
| | | T _A = +85°C | -548 |

Electrical Characteristics N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|---------------------|-----|-------|------|------|---|
| OFF CHARACTERISTICS (Note 6) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 20 | — | — | V | V _{GS} = 0V, I _D = 250μA |
| Zero Gate Voltage Drain Current | I _{DSS} | — | — | 100 | nA | @T _C = +25°C V _{DS} = 20V, V _{GS} = 0V |
| Gate-Source Leakage | I _{GSS} | — | — | ±1.0 | μA | V _{GS} = ±4.5V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 6) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 0.5 | — | 1.0 | V | V _{DS} = V _{GS} , I _D = 250μA |
| Static Drain-Source On-Resistance | R _{DS(ON)} | — | 0.3 | 0.45 | Ω | V _{GS} = 4.5V, I _D = 600mA |
| | | — | 0.4 | 0.6 | | V _{GS} = 2.5V, I _D = 500mA |
| | | — | 0.5 | 0.75 | | V _{GS} = 1.8V, I _D = 350mA |
| Forward Transfer Admittance | Y _{fs} | — | 1.4 | — | S | V _{DS} = 10V, I _D = 400mA |
| Diode Forward Voltage (Note 6) | V _{SD} | — | 0.7 | 1.2 | V | V _{GS} = 0V, I _S = 150mA |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | |
| Input Capacitance | C _{iss} | — | 60.67 | — | pF | V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz |
| Output Capacitance | C _{oss} | — | 9.68 | — | pF | |
| Reverse Transfer Capacitance | C _{rss} | — | 5.37 | — | pF | |
| Total Gate Charge (4.5V) | Q _g | — | 736.6 | — | nC | V _{GS} = 4.5V, V _{DS} = 10V, I _D = 250mA |
| Gate-Source Charge | Q _{gs} | — | 93.6 | — | nC | |
| Gate-Drain Charge | Q _{gd} | — | 116.6 | — | nC | |
| Turn-On Delay Time | t _{D(on)} | — | 5.1 | — | ns | V _{DD} = 10V, V _{GS} = 4.5V, R _L = 47Ω, R _G = 10Ω, |
| Turn-On Rise Time | t _r | — | 7.4 | — | ns | |
| Turn-Off Delay Time | t _{D(off)} | — | 26.7 | — | ns | |
| Turn-Off Fall Time | t _f | — | 12.3 | — | ns | |

Notes: 5. Device mounted on FR-4 PCB with minimum recommended pad layout.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to production testing.

N-CHANNEL - Q1

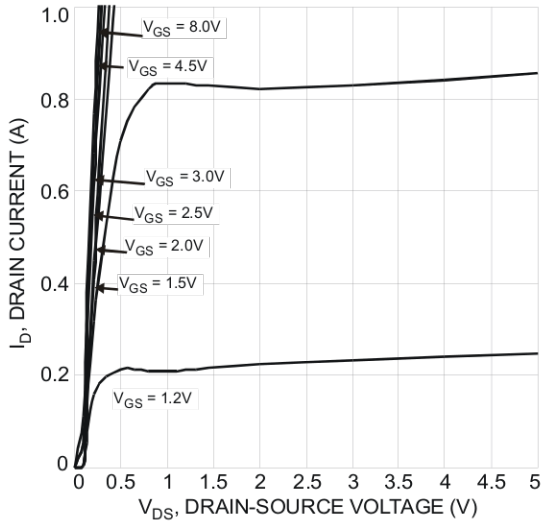


Fig. 1 Typical Output Characteristic

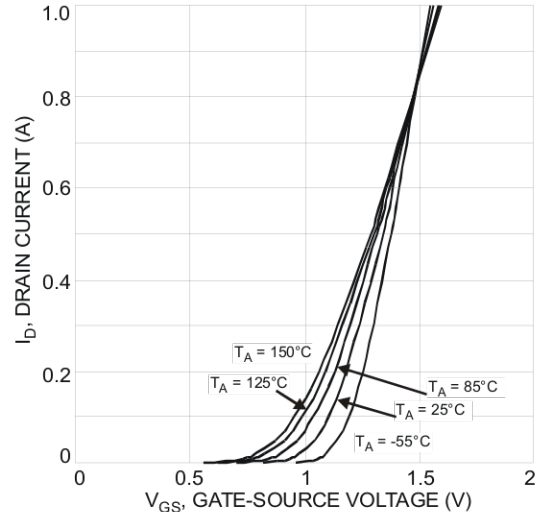


Fig. 2 Typical Transfer Characteristic

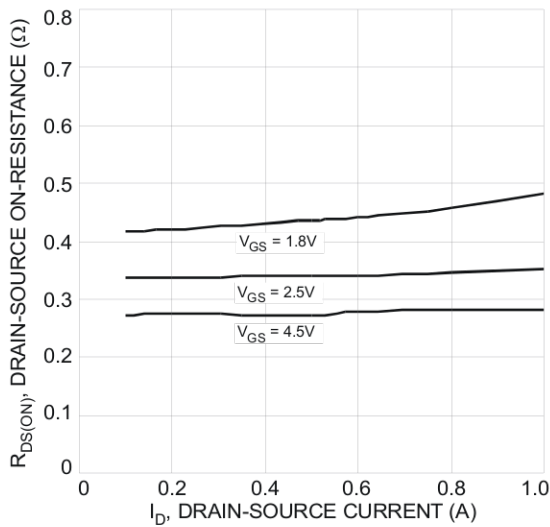


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

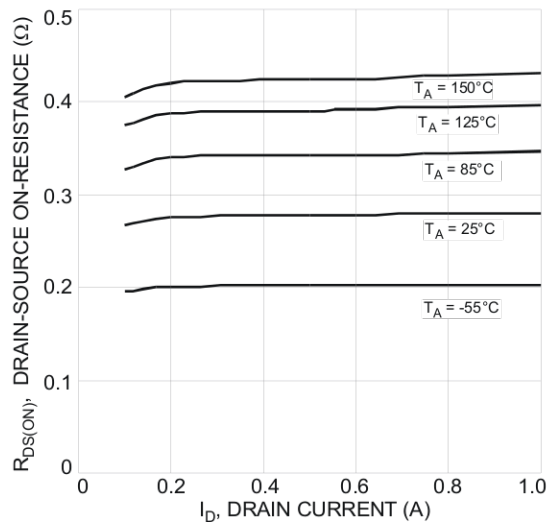


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

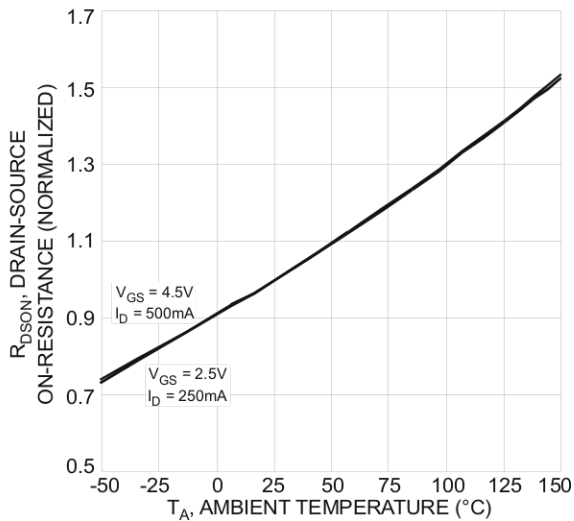


Fig. 5 On-Resistance Variation with Temperature

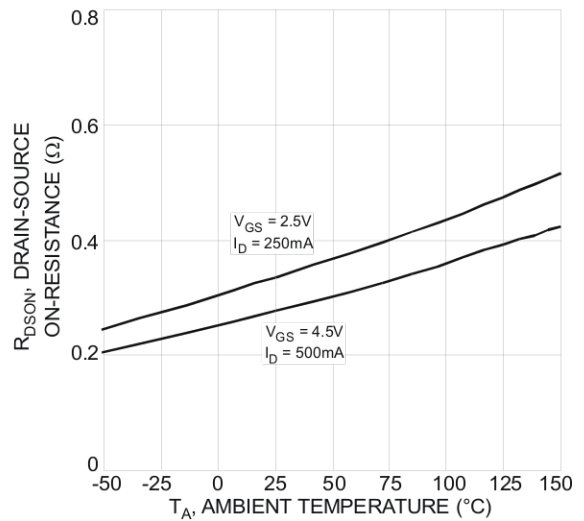


Fig. 6 On-Resistance Variation with Temperature

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N-CHANNEL – Q1 (cont.)

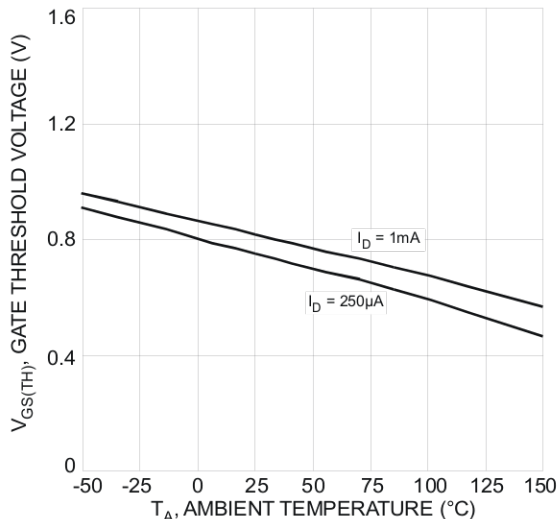


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

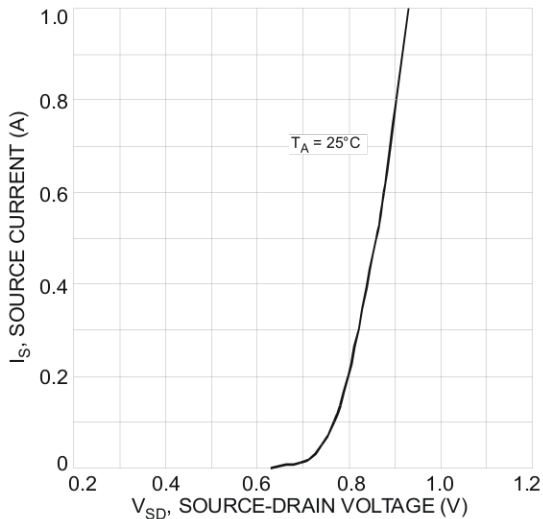


Fig. 8 Diode Forward Voltage vs. Current

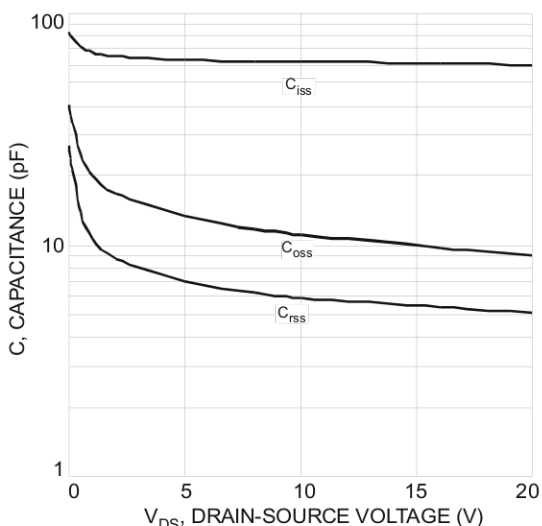


Fig. 9 Typical Total Capacitance

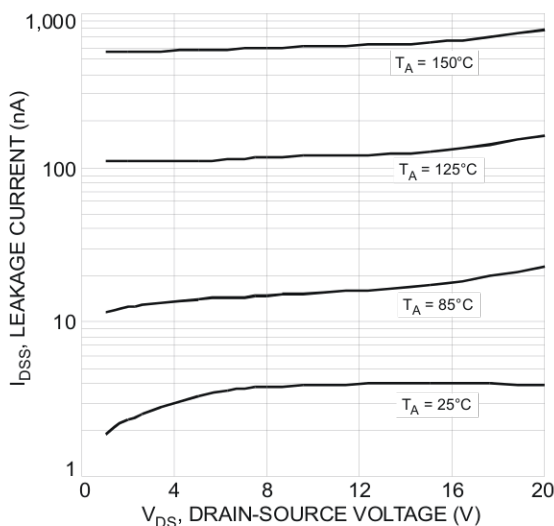


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

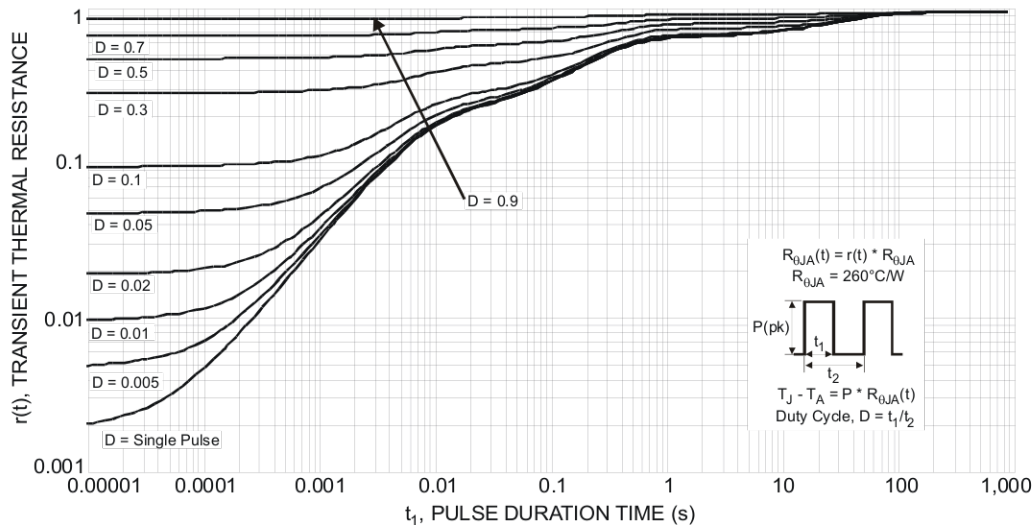


Fig. 11 Transient Thermal Response

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Electrical Characteristics P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|---------------------|------|-------|------|------|--|
| OFF CHARACTERISTICS (Note 6) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -20 | — | — | V | V _{GS} = 0V, I _D = -250μA |
| Zero Gate Voltage Drain Current | I _{DSS} | — | — | -100 | nA | V _{DS} = -20V, V _{GS} = 0V |
| Gate-Source Leakage | I _{GSS} | — | — | ±2.0 | μA | V _{GS} = ±4.5V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 6) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | -0.5 | — | -1.0 | V | V _{DS} = V _{GS} , I _D = -250μA |
| Static Drain-Source On-Resistance | R _{DS(on)} | — | 0.5 | 0.75 | Ω | V _{GS} = -4.5V, I _D = -430mA |
| | | | 0.7 | 1.05 | | V _{GS} = -2.5V, I _D = -300mA |
| | | | 1.0 | 1.5 | | V _{GS} = -1.8V, I _D = -150mA |
| Forward Transfer Admittance | Y _{fs} | — | 0.9 | — | S | V _{DS} = -10V, I _D = -250mA |
| Diode Forward Voltage (Note 6) | V _{SD} | — | -0.8 | -1.2 | V | V _{GS} = 0V, I _S = -150mA |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | |
| Input Capacitance | C _{iss} | — | 59.76 | — | pF | V _{DS} = -16V, V _{GS} = 0V, f = 1.0MHz |
| Output Capacitance | C _{oss} | — | 12.07 | — | pF | |
| Reverse Transfer Capacitance | C _{rss} | — | 6.36 | — | pF | |
| Total Gate Charge (4.5V) | Q _g | — | 622.4 | — | pC | V _{GS} = -4.5V, V _{DS} = -10V, I _D = -250mA |
| Gate-Source Charge | Q _{gs} | — | 100.3 | — | pC | |
| Gate-Drain Charge | Q _{gd} | — | 132.2 | — | pC | |
| Turn-On Delay Time | t _{D(on)} | — | 5.1 | — | ns | V _{DS} = -10V, V _{GS} = -4.5V, R _G = 10Ω, R _L = 47Ω |
| Turn-On Rise Time | t _r | — | 8.1 | — | ns | |
| Turn-Off Delay Time | t _{D(off)} | — | 28.4 | — | ns | |
| Turn-Off Fall Time | t _f | — | 20.72 | — | ns | |

Notes: 6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to production testing

P-CHANNEL – Q2

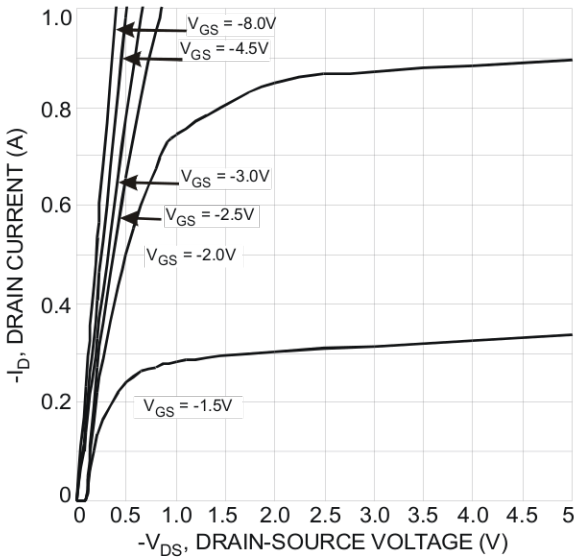


Fig. 12 Typical Output Characteristic

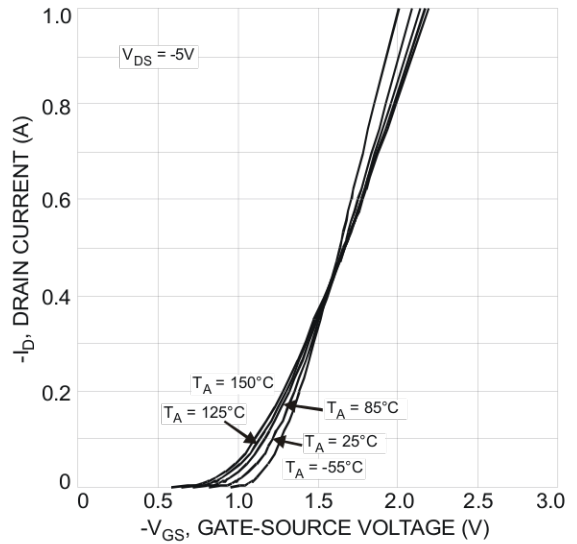


Fig. 13 Typical Transfer Characteristic

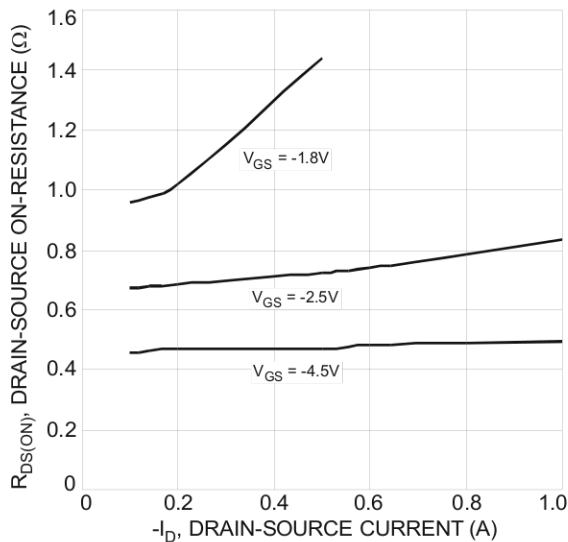


Fig. 14 Typical On-Resistance vs. Drain Current and Gate Voltage

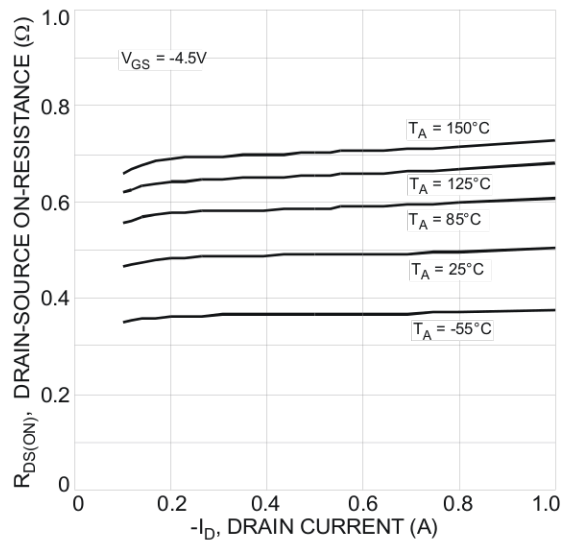


Fig. 15 Typical On-Resistance vs. Drain Current and Temperature

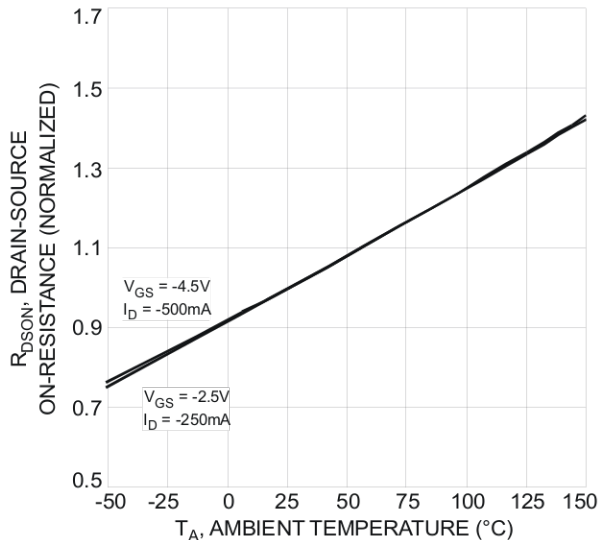


Fig. 16 On-Resistance Variation with Temperature

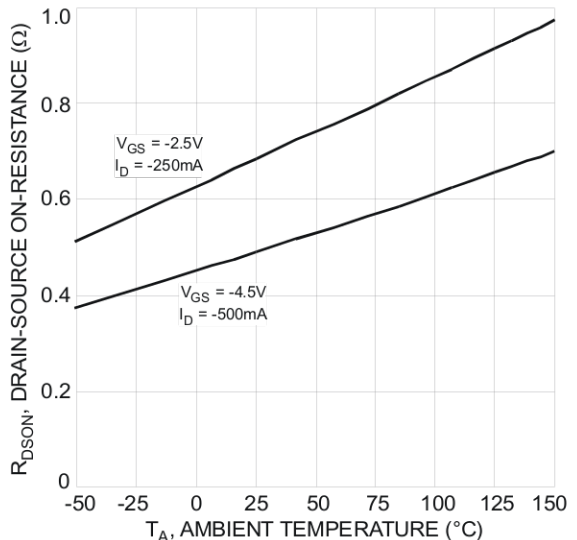


Fig. 17 On-Resistance Variation with Temperature

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P-CHANNEL – Q2 (cont.)

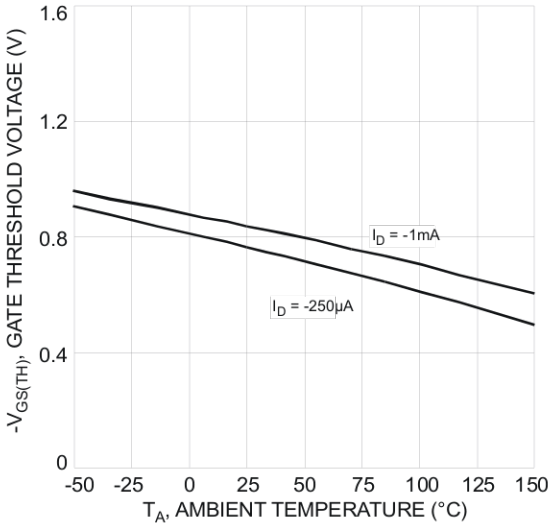


Fig. 18 Gate Threshold Variation vs. Ambient Temperature

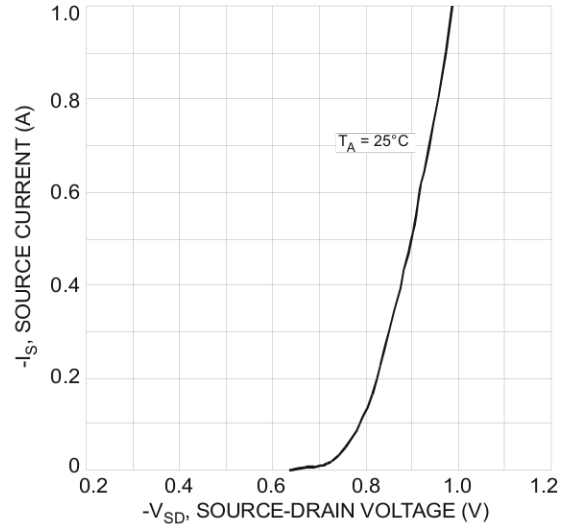


Fig. 19 Diode Forward Voltage vs. Current

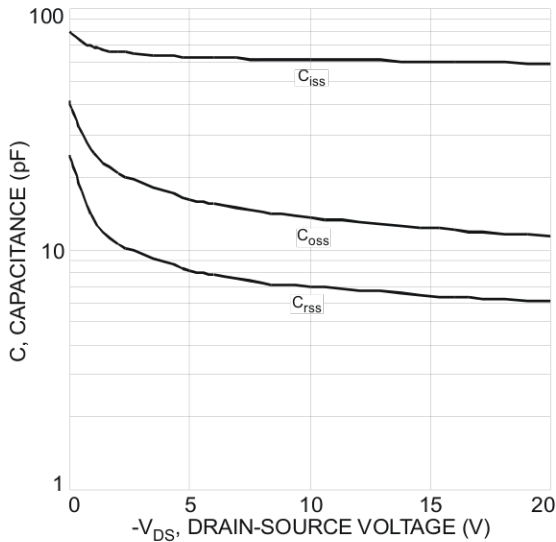


Fig. 20 Typical Total Capacitance

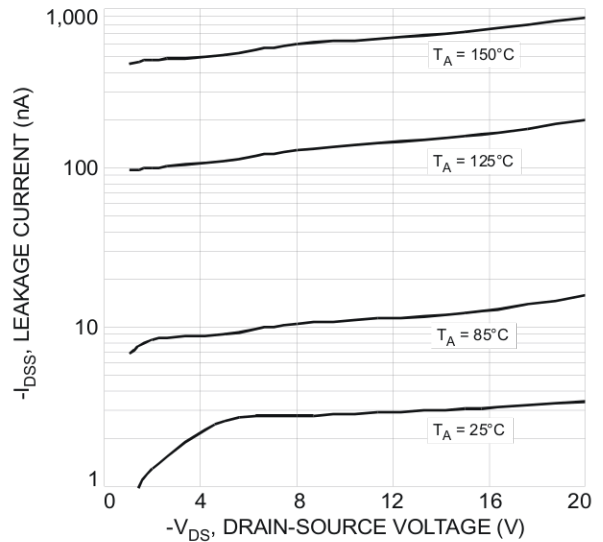


Fig. 21 Typical Leakage Current vs. Drain-Source Voltage

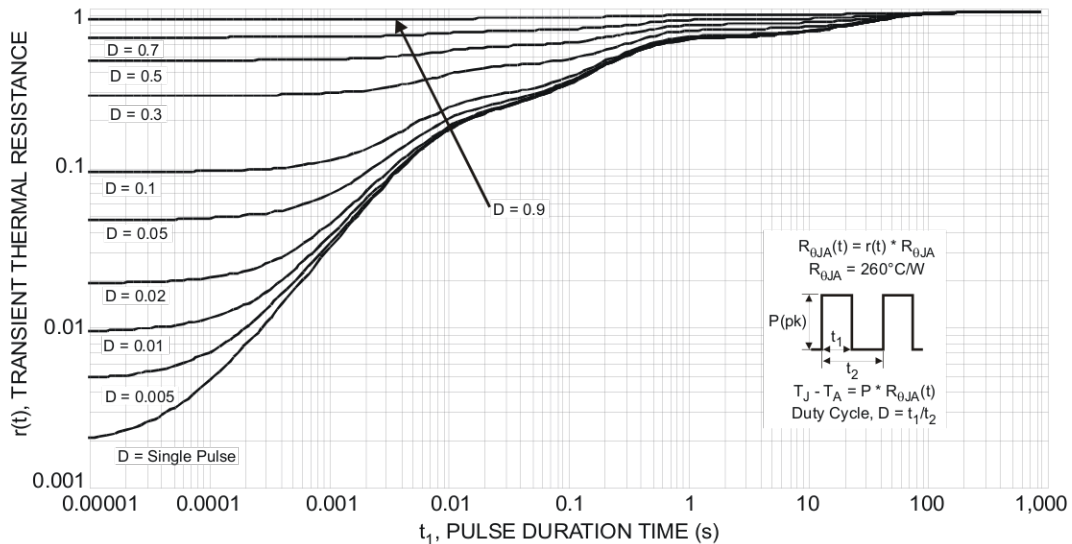


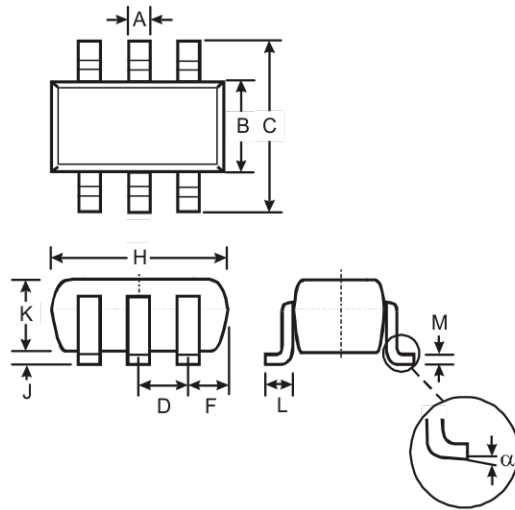
Fig. 22 Transient Thermal Response

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Package Outline Dimensions

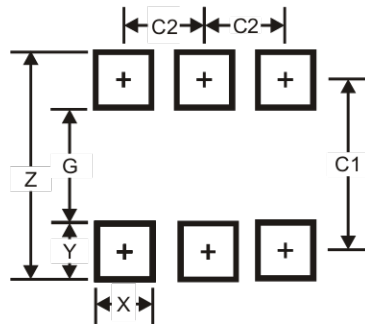
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



| SOT363 | | |
|-----------------------------|----------|------|
| Dim | Min | Max |
| A | 0.10 | 0.30 |
| B | 1.15 | 1.35 |
| C | 2.00 | 2.20 |
| D | 0.65 Typ | |
| F | 0.40 | 0.45 |
| H | 1.80 | 2.20 |
| J | 0 | 0.10 |
| K | 0.90 | 1.00 |
| L | 0.25 | 0.40 |
| M | 0.10 | 0.22 |
| α | 0° | 8° |
| All Dimensions in mm | | |

Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.5 |
| G | 1.3 |
| X | 0.42 |
| Y | 0.6 |
| C1 | 1.9 |
| C2 | 0.65 |

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